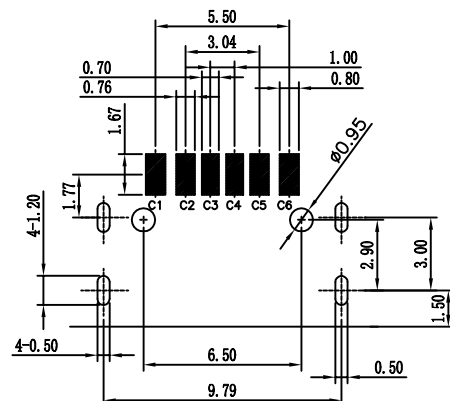
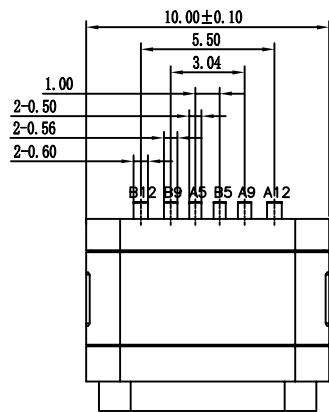
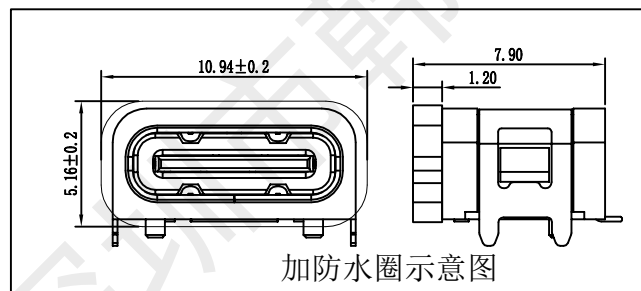
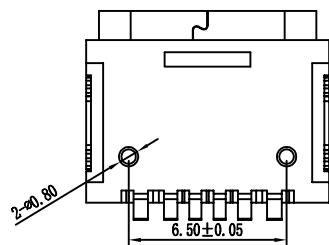
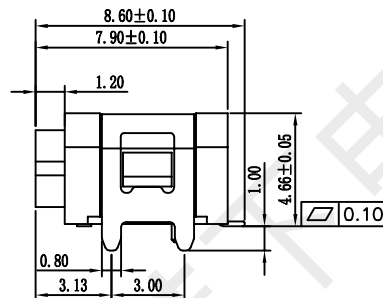
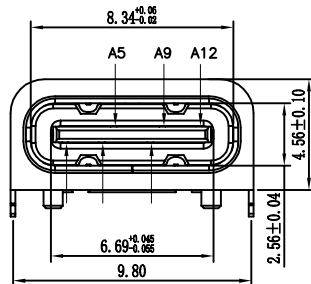




REV.	ZONE	DESCRIPTION	DESIGN	DATE
B		下板尺寸1.2改为1.0		2023/04/03



RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm



NOTE:

- MATERIAL SPECIFICATION:
 - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 - CONTACTS: COPPER ALLOY
 - MID PLATE: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
- PLATING SPECIFICATION:
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - FRONT SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - SHIELD PLATE&EMI PLATE:
 - CLEAR ONLY
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
 - CURRENT RATING: 3.0A
VOLTAGE RATING: 5.0V
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ /PIN MAX.
 - SHIELD: 50mΩ /MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25° C~+85° C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260° C.

USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
SIGNAL NAME	/	/	/	/	CC1	/	/	/	V _{bus}	/	/	GND
PIN NUMBER	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1
SIGNAL NAME	GND	/	/	V _{bus}	/	/	/	CC2	/	/	/	/

X. ±0.50	X.* ± 2*	UNITS	深圳市韩下电子有限公司	
.X ±0.30	.X* ± 1*	mm		
.XX ±0.15	.XX* ± 0.5*	MAT'L	TITLE:	
.XXX ±0.05			HX TYPE-C-31-E-01-6P FS	
		FINISH	APPD: 罗小春	DWG NO.: 1020021
		Q'TY	CHKD: 张伟	
			DR: 黄彬	SCALE SHEET REV. 1/1 1/2 B